

Abstract of the Disclosure

A method for forming an extended solder column on a contact pad of an electronic device comprises steps of (a) applying a solder seed to the contact pad; (b) contacting the seed with a surface substantially parallel to and
6 opposite the contact pad, with the seed between the surface and the pad; (c) melting the seed to wet the contact pad and the surface; (d) extending the relative separation of the surface and the contact pad, drawing the molten seed into a column; and (e) solidifying the resultant column. Further in the invention an integrated circuit (IC) assembly for mounting to a surface of a device board comprises a plurality of planar ICs interspersed with individual
12 interposers or a or continuous interposer and conductive bars for constraining the stack and providing conductive paths to the device board.